



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISC060N10NM6	Issued	27. April 2022
MA#	MA005714114		
Package	PG-TDSON-8-36	Weight*	115.55 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.976	0.84	0.84	8449	8449
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	iron	7439-89-6	0.049	0.04		423	
	non noble metal	copper	7440-50-8	48.769	42.23	42.28	422053	422603
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	391	391
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		721	
	plastics	epoxy resin	-	6.580	5.69		56942	
	inorganic material	silicondioxide	60676-86-0	34.981	30.27	36.03	302727	360390
leadfinish	non noble metal	tin	7440-31-5	1.392	1.20	1.20	12043	12043
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1677	1677
solder	non noble metal	tin	7440-31-5	0.026	0.02		222	
	noble metal	silver	7440-22-4	0.032	0.03		277	
	non noble metal	lead	7439-92-1	1.223	1.06	1.11	10583	11082
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		148	
	non noble metal	copper	7440-50-8	17.131	14.83	14.84	148257	148450
clip plating	noble metal	silver	7440-22-4	1.059	0.92	0.92	9166	9166
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			26	
	non noble metal	copper	7440-50-8	2.971	2.57	2.57	25715	25749
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com